Ground Fault Protection for 220Vac Powered Drives

Assembly Note
ZZ2
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

Assembly Note
ZZ3
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

PCB Label

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<th>Variant</th>
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<tr>
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PCB Number: TID-00442
PCB Rev: E2

These assemblies are ESD sensitive, ESD precautions shall be observed.

Texas Instruments

PCB Label

Size: 0.65" x 0.20"
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